

## ABSTRACT OF THE DISCLOSURE

A multilayered circuit board and a method of forming the multilayer circuit board are provided. In a first circuit forming process P1p, a first circuit 12a is formed on an insulating board 11a with a conductor 12a; in a circuit embedding process P2p, the first circuit 12a is embedded in the insulating board 11a so as to have a predetermined surface flatness S and a predetermined parallelism P; in a masking process P4p, a pilot hole 15, 20 for a via hole 4, 4a is masked at a part of the surface of the circuit 12a; in an insulating layer forming process P5p, an insulating material 11b is applied as a layer to the surface except the mask 14; in an insulating material layer flattening process, the surface of the insulating material layer 11b is flattened so as to have the predetermined surface flatness S and the predetermined parallelism P; and in a pilot hole forming process, the mask 14 is removed.